

REMARKS

Claims 1, 4-9, 11, 13, 15 and 17 are currently pending in the application.

35 U.S.C. § 103 Rejection:

Claims 1-2, 4-9, 13, 15, and 17 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Feilchenfeld et al, U.S. Patent 5,798,563 (hereafter 'Fed'), in view of Smith et al, U.S. Patent 5,694,297. Applicant respectfully traverses this rejection.

The cited references, taken singly or in combination, do not teach or suggest all of the elements of the independent claims. The teaching of Fed and Smith are presented in the previous office action response.

In rejecting the claims, the Examiner asserts that Fed teaches a printed circuit board (PCB) **wherein the PCB is not configured for providing core power to the IC.** The Examiner further states that Figure 1 of Fed does not **directly** electrically contact the IC and that Figure 1 shows only the IC electrically connected to a chip carrier 10. Applicant respectfully disagrees with the Examiner's assertion and submits that nothing in Fed teaches or suggests that substrate 46 (which can be a PCB as taught by Fed in column 2, lines 28-32) does not provide core power to the IC. Applicant also notes that substrate 46 does not need to be **directly** connected to the IC in order to provide core power to the IC (e.g., core power could be provided via through holes 26 which are plated with conductive plating, or alternatively filled with conductive fill, as taught in column 2, lines 3-5 of Fed). Thus, Applicant submits that a PCB can provide core power to an IC in a system such as that shown by Fed even if the IC is not **directly** connected to the IC. Furthermore, Applicant notes that Fed does not state the source of power received by carrier 10. Since no separate connections to carrier 10 are shown in Figures 1 or 2 of Fed, Applicant respectfully submits that one would readily conclude that core power is indeed provided to IC 42 by substrate 46.

The Examiner further states that Figures 2 and 3 of Smith show "a system comprising a power laminate" (108, column 5, line 6). Applicant respectfully disagrees,

and can find no teaching or suggestion in the Figures or references text that socket 108 (in Figure 2 of Smith) is a laminate structure.

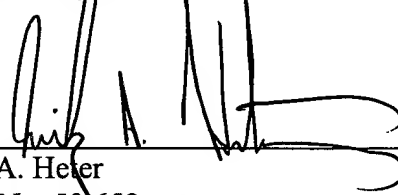
In light of the above remarks, Applicant submits that the standard for obviousness has not been met. Accordingly, removal of the 35 U.S.C. § 103(a) rejection is respectfully requested.

CONCLUSION

Applicant submits the application is in condition for allowance, and an early notice to that effect is requested.

If any fees are due, the Commissioner is authorized to charge said fees to Meyertons, Hood, Kivlin, Kowert, & Goetzel, P.C. Deposit Account No. 501505/5181-71501/BNK.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'Erik A. Heter', is written over a horizontal line.

Erik A. Heter
Reg. No. 50,652
AGENT FOR APPLICANT(S)

Meyertons, Hood, Kivlin, Kowert, & Goetzel, P.C.
P.O. Box 398
Austin, TX 78767-0398
Phone: (512) 853-8800

Date: March 1, 2004